

# CD4017B, CD4022B Types

## CMOS Counter/Dividers

High-Voltage Types (20-Volt Rating)

CD4017B—Decade Counter with  
10 Decoded Outputs

CD4022B—Octal Counter with  
8 Decoded Outputs

■ CD4017B and CD4022B are 5-stage and 4-stage Johnson counters having 10 and 8 decoded outputs, respectively. Inputs include a CLOCK, a RESET, and a CLOCK INHIBIT signal. Schmitt trigger action in the CLOCK input circuit provides pulse shaping that allows unlimited clock input pulse rise and fall times.

These counters are advanced one count at the positive clock signal transition if the CLOCK INHIBIT signal is low. Counter advancement via the clock line is inhibited when the CLOCK INHIBIT signal is high. A high RESET signal clears the counter to its zero count. Use of the Johnson counter configuration permits high-speed operation, 2-input decode-gating and spike-free decoded outputs. Anti-lock gating is provided, thus assuring proper counting sequence. The decoded outputs are normally low and go high only at their respective decoded time slot. Each decoded output remains high for one full clock cycle. A CARRY-OUT signal completes one cycle every 10 clock input cycles in the CD4017B or every 8 clock input cycles in the CD4022B and is used to ripple-clock the succeeding device in a multi-device counting chain.

### Features:

- Fully static operation
- Medium-speed operation . . . 10 MHz (typ.) at  $V_{DD} = 10\text{ V}$
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13A, "Standard Specifications for Description of 'B' Series CMOS Devices"

### Applications:

- Decade counter/decimal decode display (CD4017B)
- Binary counter/decoder
- Frequency division
- Counter control/timers
- Divide-by-N counting
- For further application information, see ICAN-6166 "COS/MOS MSI Counter and Register Design and Applications"

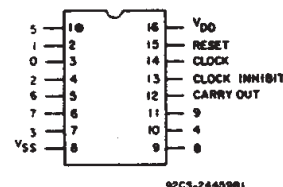
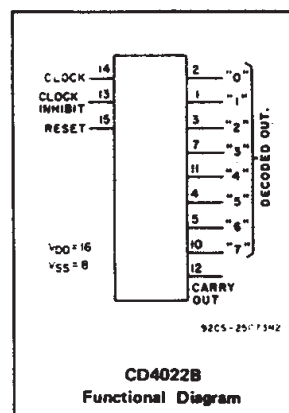
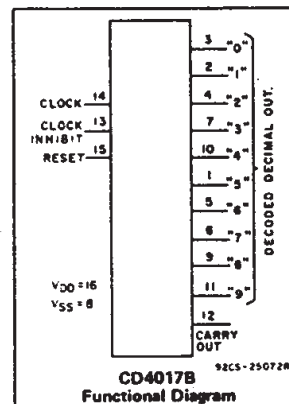
The CD4017B and CD4022B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic package (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes). The CD4017B types also are supplied in 16-lead small-outline packages (M and M96 suffixes).

### RECOMMENDED OPERATING CONDITIONS

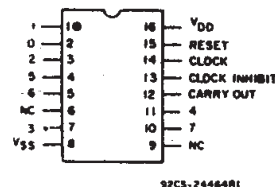
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	$V_{DD}$ (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For $T_A$ = Full Package-Temperature Range)		3	18	V
Clock Input Frequency, $f_{CL}$	5	—	2.5	MHz
	10	—	5	
	15	—	5.5	
Clock Pulse Width, $t_W$	5	200	—	ns
	10	90	—	
	15	60	—	
Clock Rise & Fall Time, $t_{rCL}$ , $t_{fCL}$	5	UNLIMITED*		
	10			
	15			
Clock Inhibit Setup Time, $t_s$	5	230	—	ns
	10	100	—	
	15	70	—	
Reset Pulse Width, $t_{RW}$	5	260	—	ns
	10	110	—	
	15	60	—	
Reset Removal Time, $t_{rem}$	5	400	—	ns
	10	280	—	
	15	150	—	

\*Only if Pin 14 is used as the clock input. If Pin 13 is used as the clock input and Pin 14 is tied high (for advancing count on negative transition of the clock), rise and fall time should be  $\leq 15\text{ }\mu\text{s}$ .



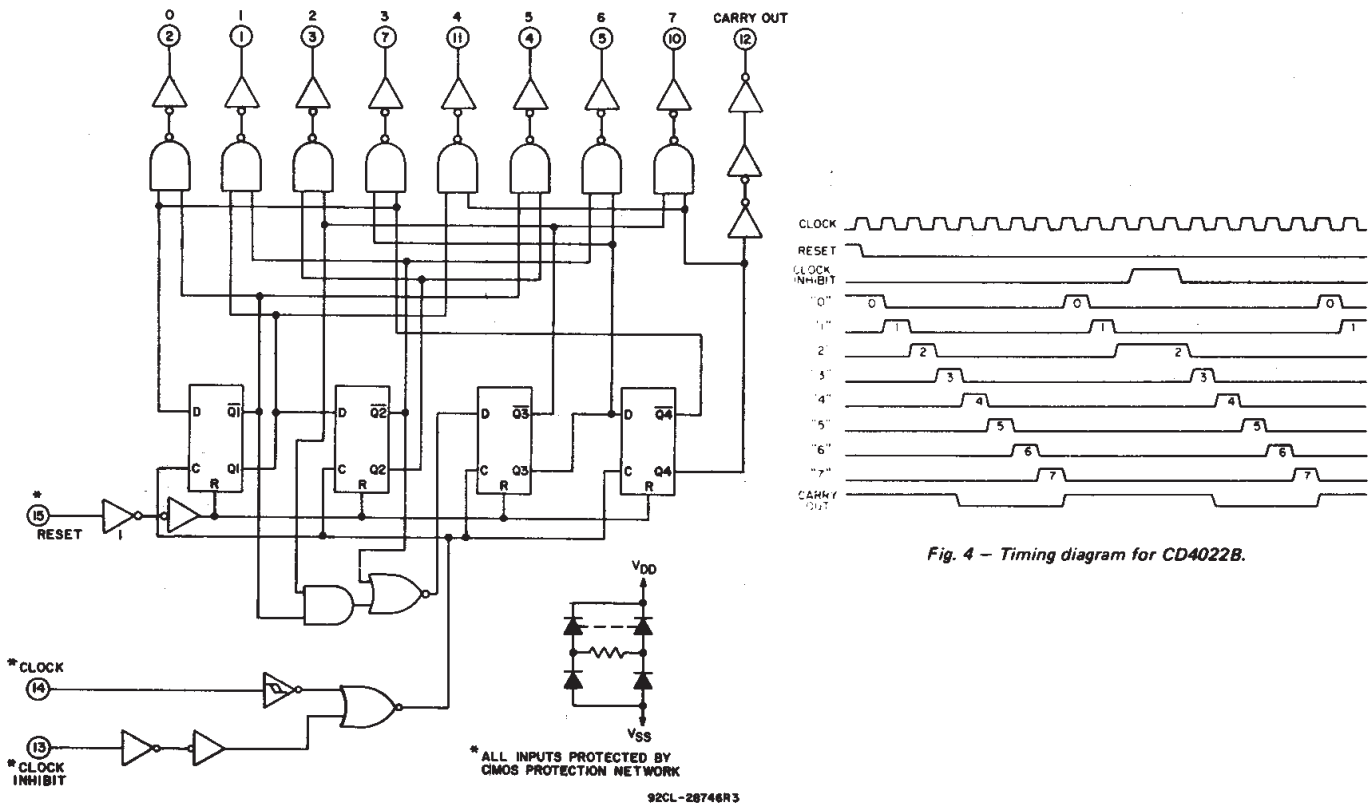
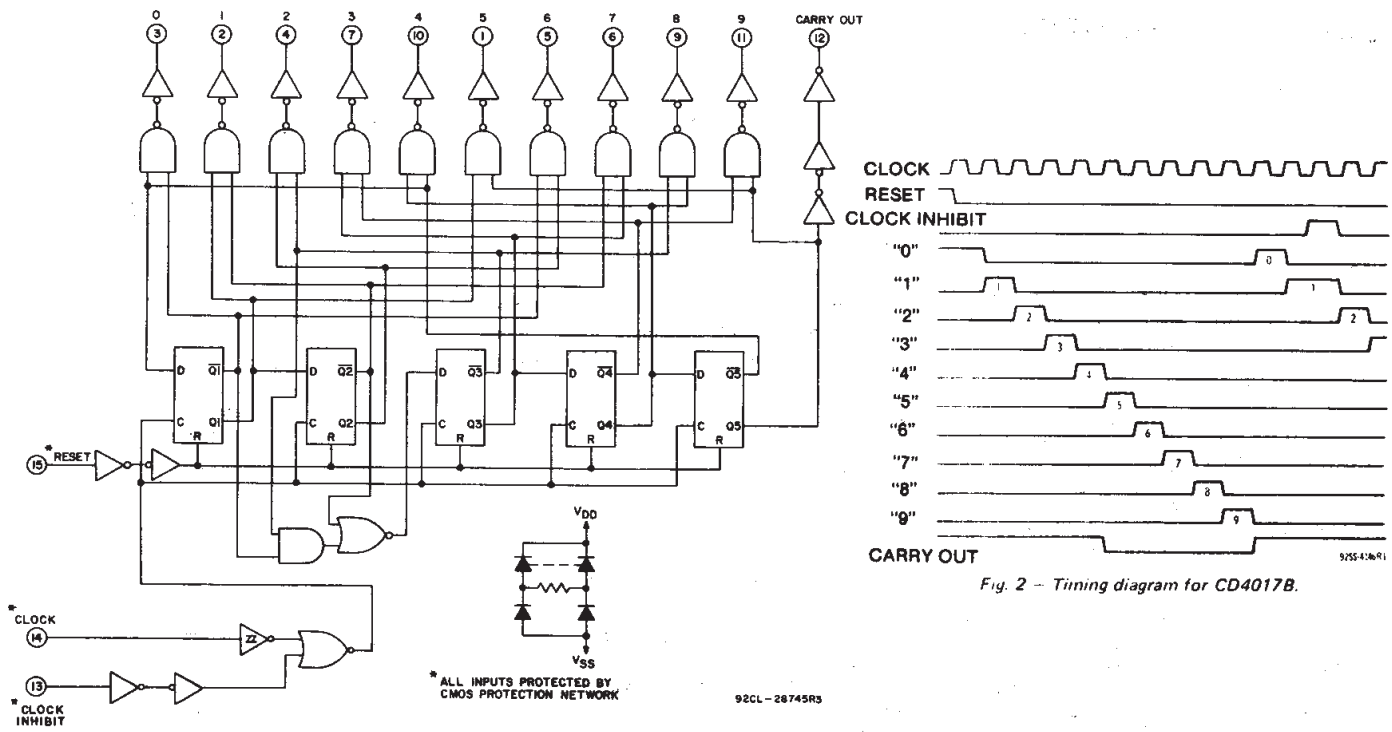
TOP VIEW  
CD4017B  
TERMINAL DIAGRAM



TOP VIEW  
NC - no connection  
CD4022B  
TERMINAL DIAGRAM

3  
COMMERCIAL CMOS  
HIGH VOLTAGE ICs

## CD4017B, CD4022B Types



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### MAXIMUM RATINGS, Absolute-Maximum Values:

#### DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )

Voltages referenced to  $V_{SS}$  Terminal) ..... -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to  $V_{DD}$  +0.5V

DC INPUT CURRENT, ANY ONE INPUT .....  $\pm 10$ mA

#### POWER DISSIPATION PER PACKAGE ( $P_D$ ):

For  $T_A = -55^\circ\text{C}$  to  $+100^\circ\text{C}$  ..... 500mW

For  $T_A = +100^\circ\text{C}$  to  $+125^\circ\text{C}$  ..... Derate Linearly at 12mW/ $^\circ\text{C}$  to 200mW

#### DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR  $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$  ..... 100mW

OPERATING-TEMPERATURE RANGE ( $T_A$ ) .....  $-55^\circ\text{C}$  to  $+125^\circ\text{C}$

STORAGE TEMPERATURE RANGE ( $T_{\text{sig}}$ ) .....  $-65^\circ\text{C}$  to  $+150^\circ\text{C}$

#### LEAD TEMPERATURE (DURING SOLDERING):

At distance  $1/16 \pm 1/32$  inch ( $1.59 \pm 0.79$ mm) from case for 10s max .....  $+265^\circ\text{C}$

### STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I <sub>DD</sub> Max.	—	0.5	5	5	5	150	150	—	0.04	5	μA
	—	0.10	10	10	10	300	300	—	0.04	10	
	—	0.15	15	20	20	600	600	—	0.04	20	
	—	0.20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I <sub>OL</sub> Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I <sub>OH</sub> Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	—	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	—	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	—	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	—	
Output Voltage: Low-Level, V <sub>OL</sub> Max.		0.5	5	0.05				—	0	0.05	V
		0.10	10	0.05				—	0	0.05	
	-	0.15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V <sub>OH</sub> Min.	-	0.5	5	4.95				4.95	5	—	V
		0.10	10	9.95				9.95	10	—	
	—	0.15	15	14.95				14.95	15	—	
Input Low Voltage V <sub>IL</sub> Max.	0.5, 4.5	—	5	1.5				—	—	1.5	V
	1.9	—	10	3				—	—	3	
	1.5, 13.5	—	15	4				—	—	4	
Input High Voltage, V <sub>IH</sub> Min.	0.5, 4.5	—	5	3.5				3.5	—	—	V
	1.9	—	10	7				7	—	—	
	1.5, 13.5	—	15	11				11	—	—	
Input Current I <sub>IN</sub> Max.	—	0.18	18	±0.1	±0.1	±1	±1	—	±10 <sup>-5</sup>	±0.1	μA

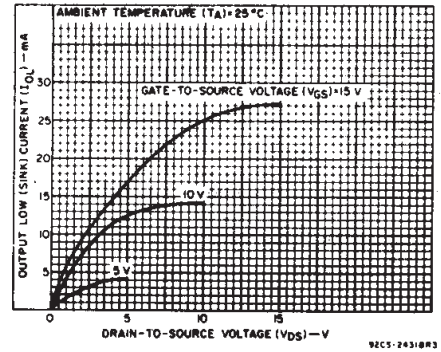


Fig. 5— Typical output low (sink) current characteristics.

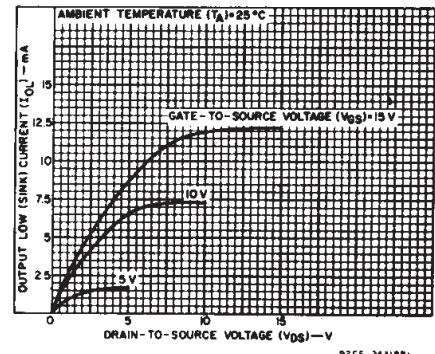


Fig. 6— Minimum output low (sink) current characteristics.

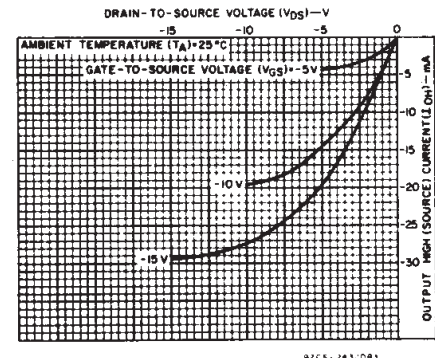


Fig. 7— Typical output high (source) current characteristics.

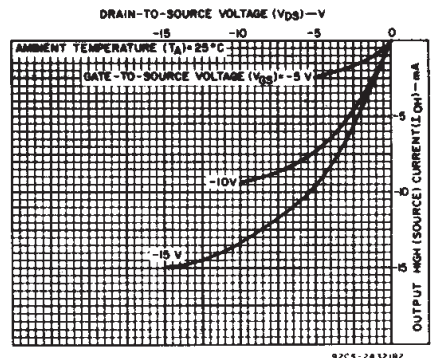


Fig. 8— Minimum output high (source) current characteristics.

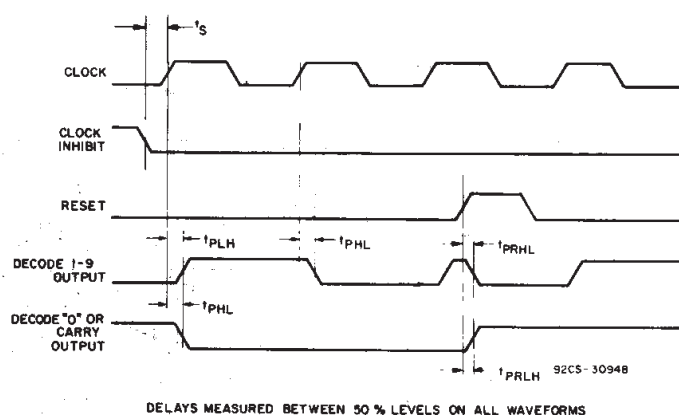
# CD4017B, CD4022B Types

## DYNAMIC ELECTRICAL CHARACTERISTICS

At  $T_A = 25^\circ\text{C}$ , Input  $t_r, t_f = 20\text{ ns}$ ,  $C_L = 50\text{ pF}$ ,  $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	CONDITIONS V <sub>DD</sub> (V)	LIMITS			UNITS
		Min.	Typ.	Max.	
CLOCKED OPERATION					
Propagation Delay Time, t <sub>PHL</sub> , t <sub>PLH</sub> Decode Out	5	—	325	650	ns
	10	—	135	270	
	15	—	85	170	
Carry Out	5	—	300	600	ns
	10	—	125	250	
	15	—	80	160	
Transition Time, t <sub>THL</sub> , t <sub>TLH</sub> Carry Out or Decode Out Line	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Maximum Clock Input Frequency, f <sub>CL</sub> *	5	2.5	5	—	MHz
	10	5	10	—	
	15	5.5	11	—	
Minimum Clock Pulse Width, t <sub>W</sub>	5	—	100	200	ns
	10	—	45	90	
	15	—	30	60	
Clock Rise or Fall Time, t <sub>rCL</sub> , t <sub>fCL</sub>	5, 10, 15	UNLIMITED			
Minimum Clock Inhibit to Clock Setup Time, t <sub>s</sub>	5	—	115	230	ns
	10	—	50	100	
	15	—	35	70	
Input Capacitance, C <sub>IN</sub>	Any Input	—	5	—	pF
RESET OPERATION					
Propagation Delay Time, t <sub>PHL</sub> , t <sub>PLH</sub> Carry Out or Decode Out Lines	5	—	265	530	ns
	10	—	115	230	
	15	—	85	170	
Minimum Reset Pulse Width, t <sub>W</sub>	5	—	130	260	ns
	10	—	55	110	
	15	—	30	60	
Minimum Reset Removal Time	5	—	200	400	ns
	10	—	140	280	
	15	—	75	150	

\* Measured with respect to carry output line.



DELAYS MEASURED BETWEEN 50% LEVELS ON ALL WAVEFORMS

Fig. 9 - Propagation delay, setup, and reset removal time waveforms.

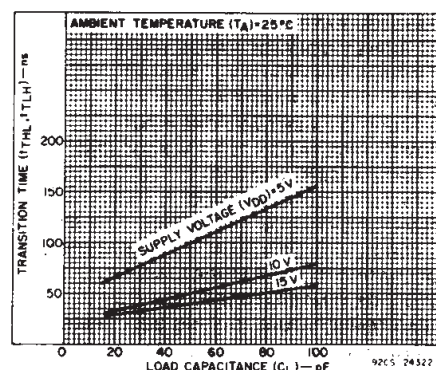


Fig. 10 - Typical transition time as a function of load capacitance.

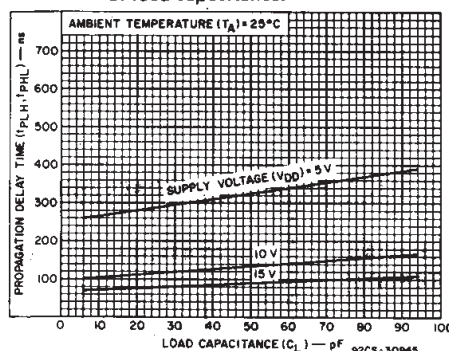


Fig. 11 - Typical propagation delay time as a function of load capacitance (clock to decode output).

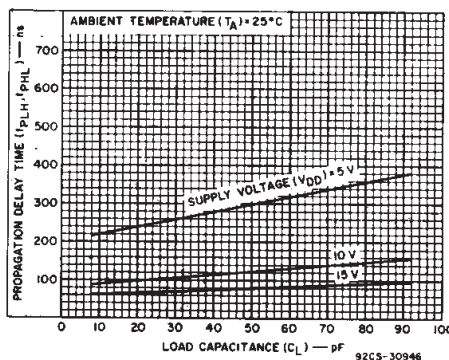


Fig. 12 - Typical propagation delay time as a function of load capacitance (clock to carry-out).

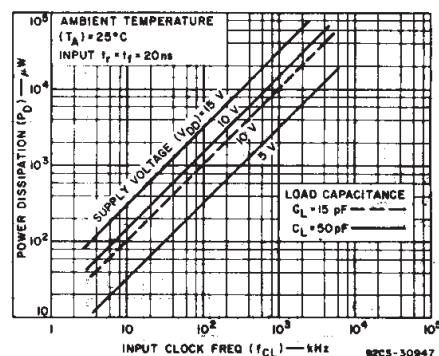


Fig. 13 - Typical dynamic power dissipation as a function of clock input frequency.

## CD4017B, CD4022B Types

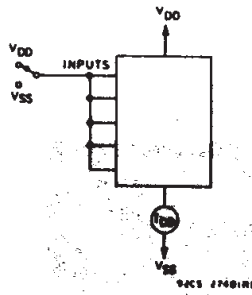


Fig. 14 - Quiescent device current test circuit.

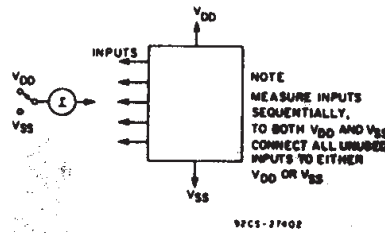


Fig. 15 - Input leakage current.

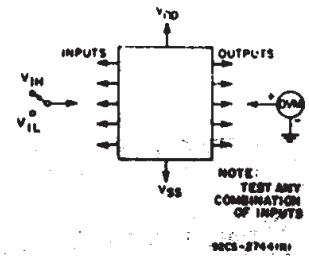


Fig. 16 - Input voltage test circuit.

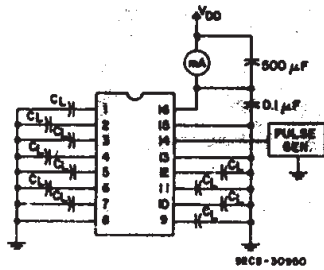


Fig. 17 - Dynamic power dissipation test circuit.

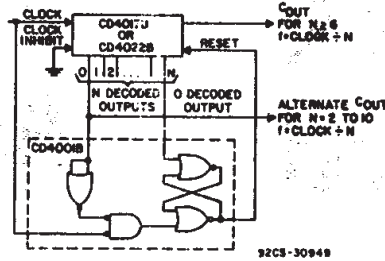


Fig. 18 - Divide by N counter ( $N \leq 10$ ) with N decoded outputs.

When the  $N^{\text{th}}$  decoded output is reached ( $N^{\text{th}}$  clock pulse) the S-R flip flop (constructed from two NOR gates of the CD4001B) generates a reset pulse which clears the CD4017B or CD4022B to its zero count. At this time, if the  $N^{\text{th}}$  decoded output is greater than or equal to 6 in the CD4017B or 5 in the CD4022B; the  $C_{OUT}$  line goes high to clock the next CD4017B or CD4022B counter section. The "0" decoded output also goes high at this time. Coincidence of the clock low and decoded "0" output low resets the S-R flip flop to enable the CD4017B or CD4022B. If the  $N^{\text{th}}$  decoded output is less than 6 (CD4017B) or 5 (CD4022B), the  $C_{OUT}$  line will not go high and, therefore, cannot be used. In this case "0" decoded output may be used to perform the clocking function for the next counter.

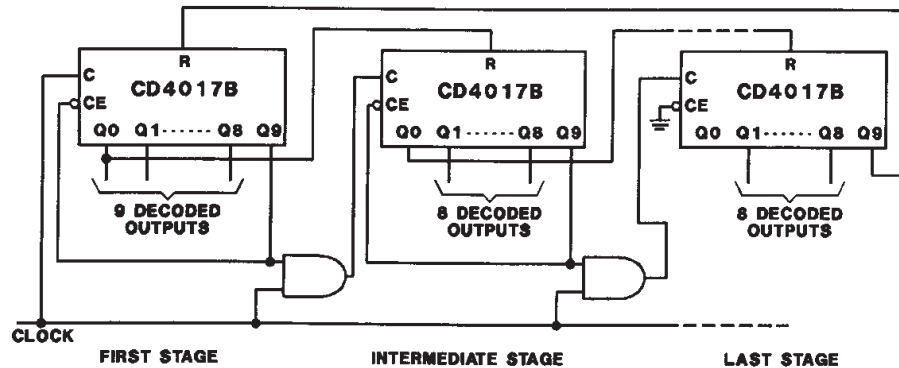
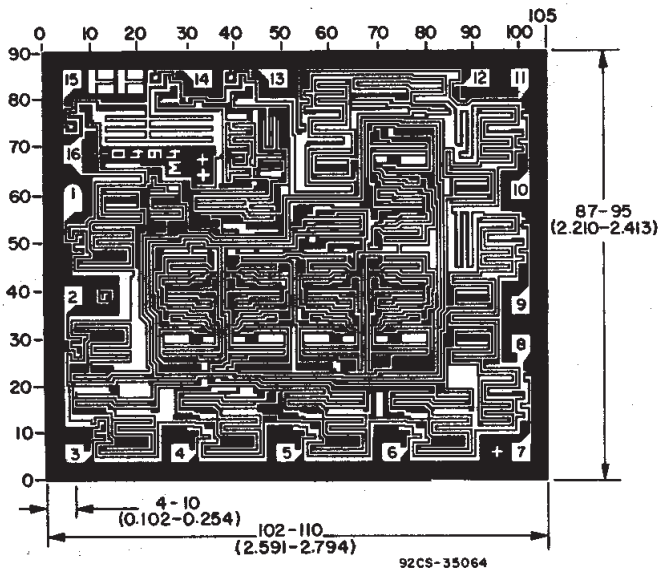


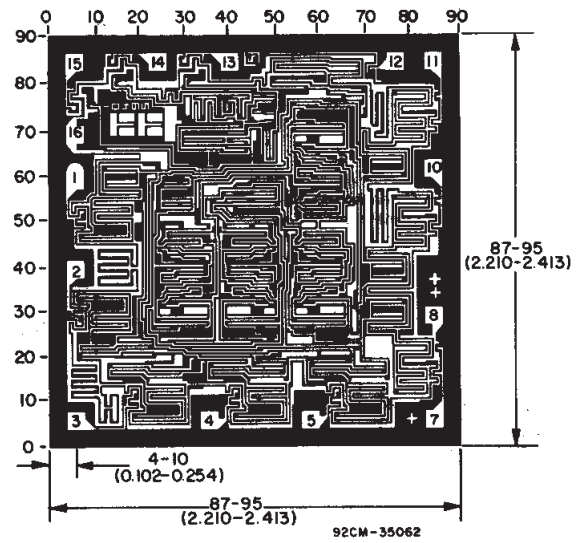
Fig. 19 - Cascading the CD4017B.

## CD4017B, CD4022B Types

### CHIP DIMENSIONS AND PAD LAYOUTS



CD4017BH



CD4022BH

*Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).*



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
89270AKB3T	OBSOLETE			0		TBD	Call TI	Call TI	
CD4017BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4017BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4017BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD4017BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD4017BF3AS2534	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
CD4017BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
CD4017BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4017BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4022BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4022BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD4022BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD4022BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4022BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
JM38510/05651BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/05651BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.



(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF CD4017B, CD4017B-MIL, CD4022B, CD4022B-MIL :**

● Catalog: [CD4017B](#), [CD4022B](#)

● Military: [CD4017B-MIL](#), [CD4022B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4017BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4017BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4017BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD4022BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4022BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4017BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4017BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4017BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0
CD4022BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4022BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



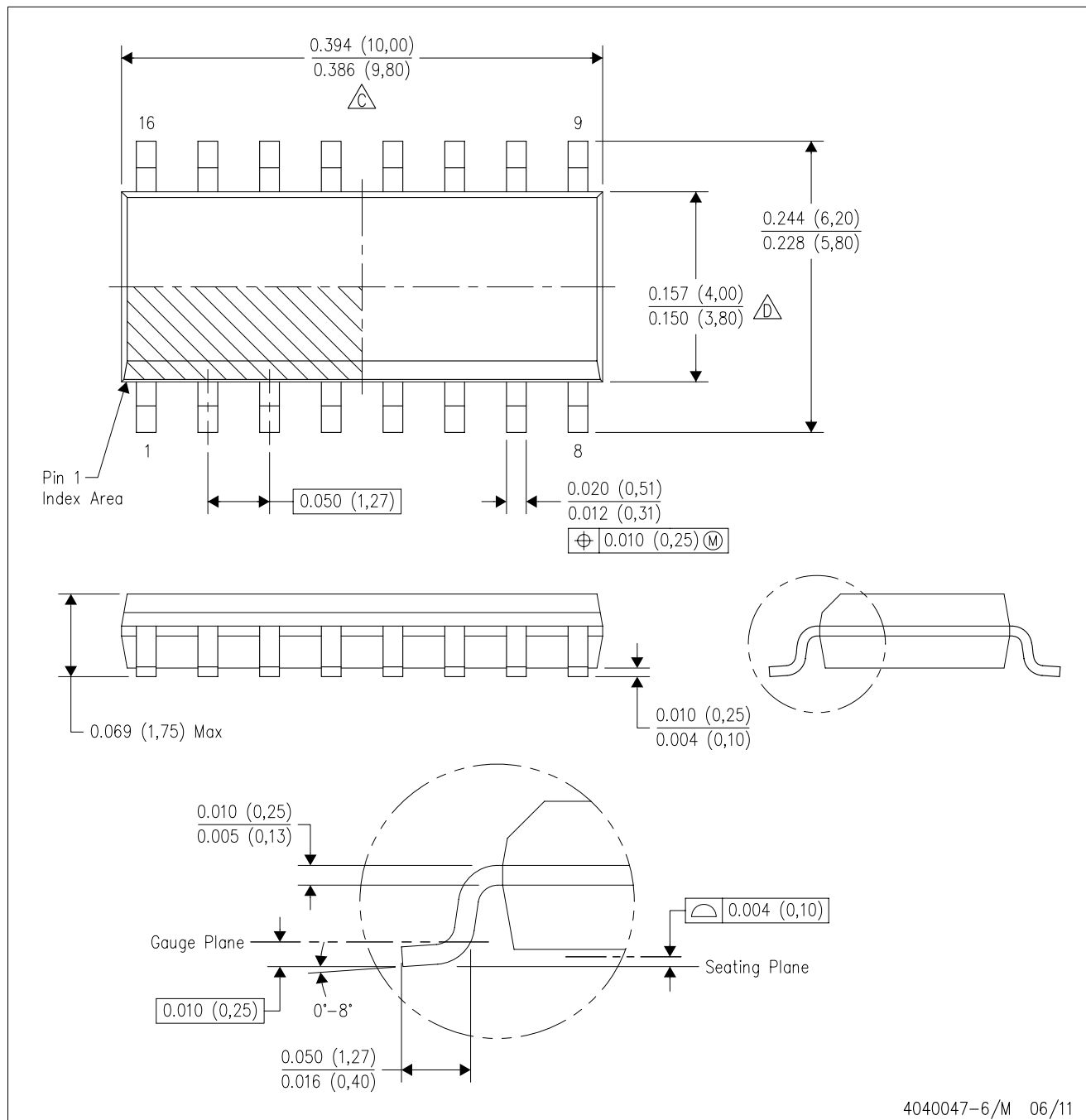
4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

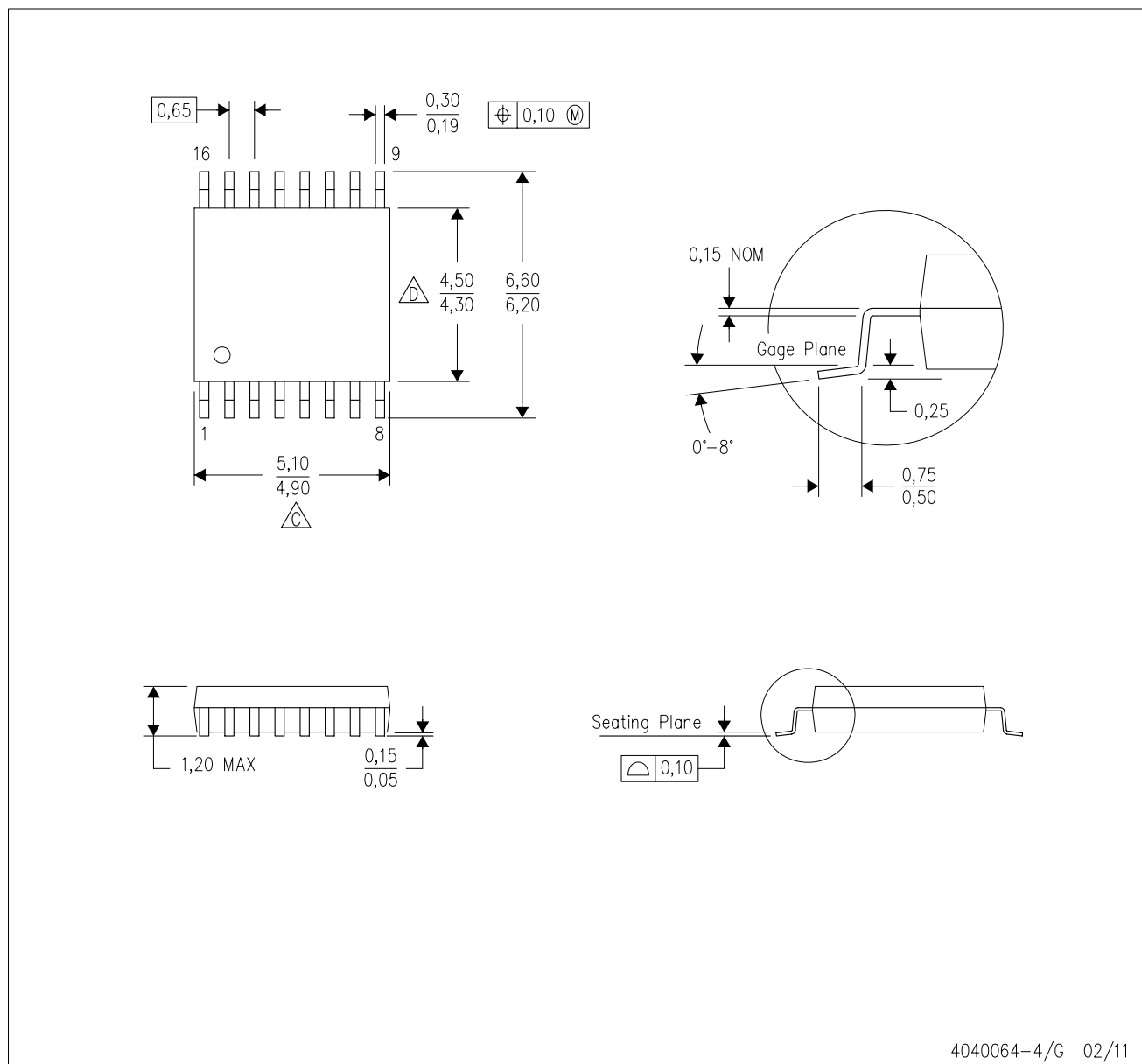
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

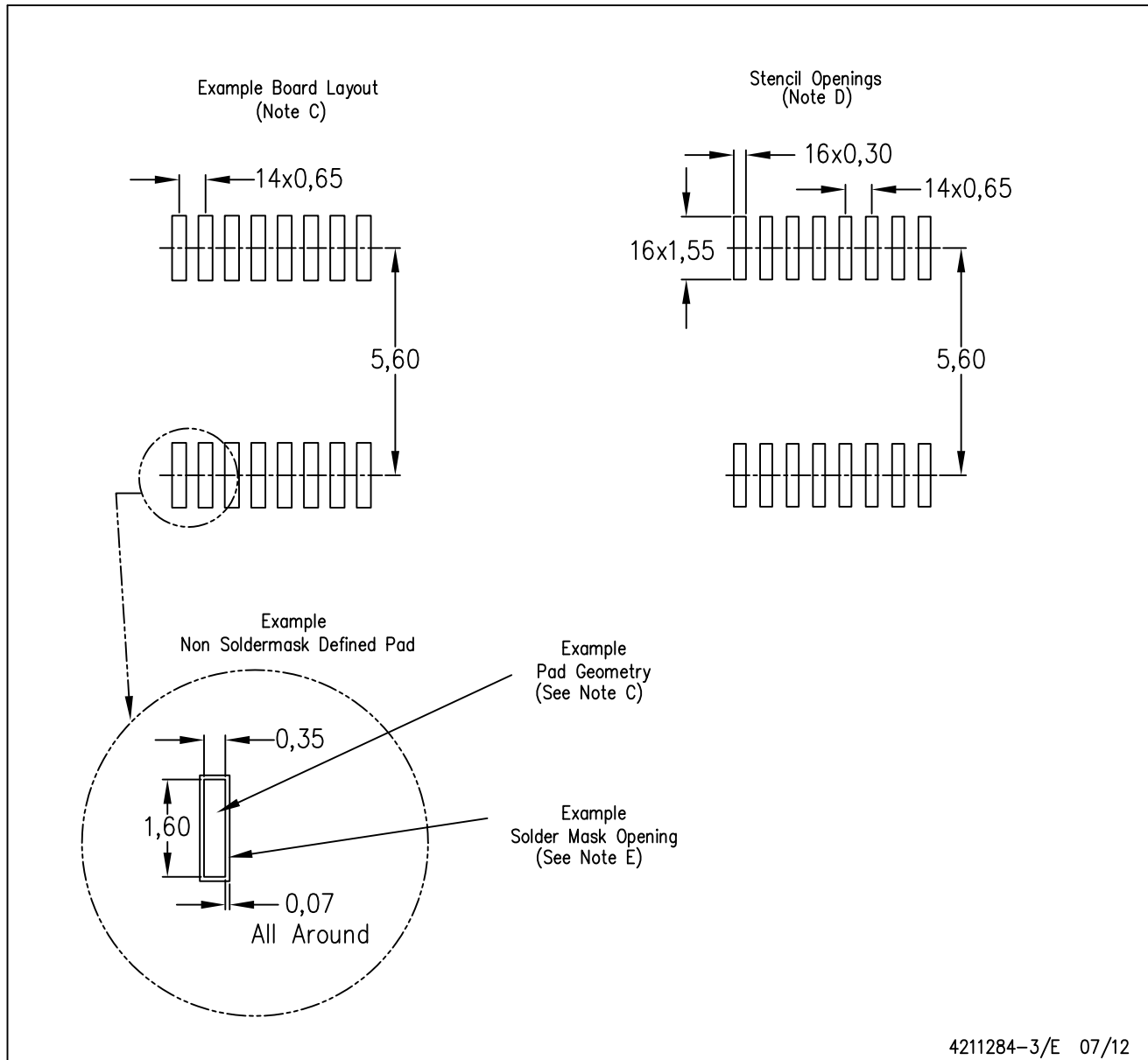
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - $\Delta$  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - $\Delta$  D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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